

# Tzong-Lin Wu

## List of Publications by Year in descending order

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253  
papers

4,219  
citations

159358

30  
h-index

143772

57  
g-index

254  
all docs

254  
docs citations

254  
times ranked

1777  
citing authors

#	ARTICLE	IF	CITATIONS
1	A Novel Compact Single-Stage Absorption Common-Mode Filter. IEEE Transactions on Electromagnetic Compatibility, 2022, 64, 111-118.	1.4	11
2	Wideband Reconfigurable Power Divider/Combiner in 40-nm CMOS for 5G mmW Beamforming System. IEEE Transactions on Microwave Theory and Techniques, 2022, 70, 1410-1422.	2.9	5
3	A Novel Absorptive Power Delivery Network for Power Noise Mitigation. IEEE Transactions on Electromagnetic Compatibility, 2022, 64, 536-542.	1.4	2
4	A Compact Symmetrical Single-Cell Bidirectional Absorption Common-Mode Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 655-664.	1.4	4
5	A 0.6-dB Low Loss and 36°165 GHz Wideband Phase Difference Sub-THz Coupler in 0.18- $\mu$ m CMOS. IEEE Microwave and Wireless Components Letters, 2022, 32, 531-534.	2.0	0
6	A planar High-efficient W-band Substrate-Integrated-Waveguide Cavity-backed Slot Antenna Array. , 2022, , .		0
7	Poles and Stability of Full-Wave PEEC. IEEE Transactions on Antennas and Propagation, 2021, 69, 950-961.	3.1	3
8	Significant Crosstalk Reduction in High-Density Hollow Dielectric Waveguides by Photonic Crystal Fence. IEEE Transactions on Microwave Theory and Techniques, 2021, 69, 1316-1326.	2.9	4
9	Extraction of Complex Permittivity of Dielectrics on Package from W-band to D-band. , 2021, , .		4
10	Bridging the Gap Between Academia and Industry: MOST 6G Research Program in Taiwan. , 2021, , .		0
11	Extremely Low-Loss Planar Transition From Hollow Dielectric Waveguide to Printed Circuit Board for Millimeter-Wave Interconnect. IEEE Transactions on Microwave Theory and Techniques, 2021, 69, 4010-4020.	2.9	4
12	Corrections to "A Fully Integrated Arbitrary Power Divider on Printed Circuit Board by a Novel SMD-Resistor-Free Isolation Network". IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1514-1514.	1.4	0
13	An Ultrawideband Common-Mode Filter with Cascaded Mushroom-like Structures. , 2021, , .		1
14	Eye Comparison Between Unencoded and 128b/130b-encoded NRZ Signals. , 2021, , .		0
15	A Novel Circuit Architecture of Bidirectional Common-Mode Noise Absorption Circuit. IEEE Transactions on Microwave Theory and Techniques, 2020, 68, 1476-1486.	2.9	12
16	Miniaturized Dual-Band FSS Suitable for Curved Surface Application. IEEE Antennas and Wireless Propagation Letters, 2020, 19, 2265-2269.	2.4	29
17	EMI Reduction Control Based on 8b/10b. , 2020, , .		0
18	A Cost-efficient Air-Filled Substrate Integrated Ridge Waveguide for mmWave Application. , 2020, , .		1

#	ARTICLE	IF	CITATIONS
19	A Fully Integrated Arbitrary Power Divider on Printed Circuit Board by a Novel SMD-Resistor-Free Isolation Network. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1889-1901.	1.4	6
20	Balanced Bandpass Filter With Common-Mode Reflectionless Feature by Terminated Coupled Lines. IEEE Transactions on Electromagnetic Compatibility, 2020, 62, 1090-1097.	1.4	9
21	An Improved Method of Finding Complex Permittivity of Lossy Liquids. , 2020, , .		0
22	Novel Absorptive Balanced Bandpass Filters Using Resistive Loaded Transmission Lines. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 745-753.	1.4	14
23	A Synthesized Method for Common-Mode Noise Suppression Filters With Specified Common-Mode and Differential Mode Response. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 893-902.	1.4	21
24	A Resistor-Free $N$ -Way Power Divider With Simultaneous Output Matching and Isolation. IEEE Microwave and Wireless Components Letters, 2019, 29, 523-525.	2.0	11
25	A High-Performance Common-Mode Noise Absorption Circuit Based on Phase Modification Technique. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 4394-4403.	2.9	13
26	Analysis and Design Method of a Novel Absorptive Common-Mode Filter. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 1826-1835.	2.9	23
27	Direct Simulation of the Full-Wave Partial Element Equivalent Circuit Using Standard SPICE [Application Notes]. IEEE Microwave Magazine, 2019, 20, 22-34.	0.7	7
28	Synthesized Method of Dual-Band Common-Mode Noise Absorption Circuits. IEEE Transactions on Microwave Theory and Techniques, 2019, 67, 1392-1401.	2.9	20
29	A mm-Wave Low-Loss Transition from Microstrip Line to Air-Filled Substrate Integrated Waveguide on Printed Circuit Board Technology. , 2019, , .		4
30	Enhanced Power and Signal Integrity Through Layout Optimization of High-Speed Memory Systems. , 2019, , .		2
31	Improvement of Power and Signal Integrity through Layer Assignment in High-Speed Memory Systems. , 2019, , .		1
32	Miniaturized Quarter-Wavelength Resonator for Common-Mode Filter Based on Pattern Ground Structure. , 2019, , .		1
33	Balanced-to-Balanced and Balanced-to-Unbalanced Power Dividers With Ultra-Wideband Common-Mode Rejection and Absorption Based on Mode-Conversion Approach. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 306-316.	1.4	17
34	Design and Modeling of a Compact Partially Transmissible Resistor-Free Absorptive Frequency Selective Surface for Wi-Fi Applications. IEEE Transactions on Antennas and Propagation, 2019, 67, 1306-1311.	3.1	9
35	Design of a Broadband Common-Mode Filter With Four Transmission Zeros. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1052-1060.	1.4	10
36	EMI-Reduction Coding Based on 8b/10b. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1007-1014.	1.4	1

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37	Design and Analysis of an Ultraminiaturized Frequency Selective Surface With Two Arbitrary Stopbands. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 1447-1456.	1.4	32
38	Codesign of Electrostatic Discharge Protection Device and Common Mode Suppression Circuit on Printed Circuit Board. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1095-1101.	1.4	5
39	Dual-band WLAN MIMO antenna with a decoupling element for full-metallic bottom cover tablet computer applications. Microwave and Optical Technology Letters, 2018, 60, 1245-1251.	0.9	9
40	Broadband Eight-Port Forward-Wave Directional Couplers and Four-Way Differential Phase Shifter. IEEE Transactions on Microwave Theory and Techniques, 2018, 66, 2161-2169.	2.9	10
41	Ultracompact Via-Based Absorptive Frequency-Selective Surface for 5-GHz Wi-Fi With Passbands and High-Performance Stability. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 41-49.	1.4	16
42	Message from the Incoming Editor-in-Chief. IEEE Transactions on Electromagnetic Compatibility, 2018, 60, 1617-1618.	1.4	0
43	Signal/Power Integrity Co-Simulation of DDR3 Memory Module. , 2018, , .		7
44	Investigation on Degradation of Common Mode Noise Suppression with Electrostatic Discharge Protection Array. , 2018, , .		0
45	An Electromagnetic Bandgap Structure Integrated With RF LNA Using Integrated Fan-Out Wafer-Level Package for Gigahertz Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2018, 66, 5482-5490.	2.9	15
46	A Common-Mode Filter with Three Alterable and Designable Transmission Zeroes. , 2018, , .		0
47	Modularized prototype of 5G mmWave base station system at 38 GHz. , 2018, , .		2
48	An eye diagram improvement method using simulation annealing algorithm. , 2018, , .		3
49	A Resistor-Free Absorptive Common-Mode Filter Using Gap-Coupled Resonator. IEEE Microwave and Wireless Components Letters, 2018, 28, 885-887.	2.0	15
50	A Novel Absorptive Common-Mode Filter for Cable Radiation Reduction. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 511-518.	1.4	29
51	An Accurate and Fast Substrate Noise Prediction Method With Octagonal TSV Model for 3-D ICs. IEEE Transactions on Electromagnetic Compatibility, 2017, 59, 1549-1557.	1.4	5
52	Analysis of Peak and Statistical Spectrum of Random Nonreturn-to-Zero Digital Signals. IEEE Transactions on Electromagnetic Compatibility, 2017, 59, 2002-2013.	1.4	0
53	The competitions of electromagnetic for undergraduate students in Taiwan: Taiwan creative electromagnetic implementation competition T-CEIC. , 2017, , .		0
54	A Novel and Compact Eight-Port Forward-Wave Directional Coupler With Arbitrary Coupling Level Design Using Four-Mode Control Technology. IEEE Transactions on Microwave Theory and Techniques, 2017, 65, 467-475.	2.9	22

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55	EMI-reduction coding based on 8b/10b. , 2017, , .		4
56	EBG-Based Grid-Type PDN on Interposer for SSN Mitigation in Mixed-Signal System-in-Package. IEEE Microwave and Wireless Components Letters, 2017, 27, 1053-1055.	2.0	8
57	A modal-analysis-based prediction method for radiation power in differential channels with discontinuity. , 2017, , .		1
58	A super broadband DGS-based common-mode filter with a compact dimension. , 2017, , .		0
59	A simple method to improve signal integrity of electrostatic discharge protection devices. , 2017, , .		1
60	Novel absorptive design of common-mode filter at desired frequency band. , 2016, , .		6
61	Balanced bandpass filter with reflectionless common-mode suppression. , 2016, , .		5
62	A radiation prediction method based on partial element equivalent circuit. , 2016, , .		0
63	Balanced bandpass filter with intrinsic common mode suppression using slot coupled lines and microstrip loading lines. , 2016, , .		3
64	E-shape resonator dualband common mode filter. , 2016, , .		3
65	Design and modeling of an absorptive frequency selective surface with several transmissive bands. , 2016, , .		2
66	A balanced-to-balanced power divider with common-mode noise absorption. , 2016, , .		3
67	Compact Cascaded-Spiral-Patch EBG Structure for Broadband SSN Mitigation in WLAN Applications. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 2740-2748.	2.9	19
68	A Resonator-Based Suppressor for Mitigating the Noise Transfer on Metal Plates for Control of Electromagnetic Interference. IEEE Microwave and Wireless Components Letters, 2016, 26, 906-908.	2.0	2
69	A Rigorous Proof on the Radiation Resistance in Generalized PEEC Model. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 4091-4097.	2.9	14
70	Beamforming broadside antenna array for 60-GHz technology. , 2016, , .		4
71	An Ultracompact TSV-Based Common-Mode Filter (TSV-CMF) in Three-Dimensional Integrated Circuits (3-D ICs). IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 1128-1135.	1.4	28
72	Promoting Effective Education in Electromagnetics: Taiwan's School of Accessible and Visualized Electromagnetics Formed [Education Corner]. IEEE Antennas and Propagation Magazine, 2016, 58, 99-129.	1.2	6

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73	A Quadruplet-Resonator-Based Ferrite-Free Choke for Suppressing Noise Currents on Cable Shielding. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 86-95.	2.9	1
74	Investigation of the Radiated Emissions From High-Speed/High-Density Connectors. IEEE Transactions on Electromagnetic Compatibility, 2016, 58, 220-230.	1.4	6
75	SAVE and iEMPT: The EM revitalization program in Taiwan. , 2015, , .		0
76	Effective current distribution analysis method for multiconductor-transmission-line (MTL) system with arbitrary conductor number variation. , 2015, , .		0
77	Post-fabricated EBG tape on electronic devices for RFI mitigation in WLAN bands. , 2015, , .		0
78	A New Broadband Common-Mode Noise Absorption Circuit for High-Speed Differential Digital Systems. IEEE Transactions on Microwave Theory and Techniques, 2015, 63, 1894-1901.	2.9	56
79	Transmission-line based modeling for conformal shielding in advance system-in-package (SiP). , 2015, , .		3
80	Prediction of near-field shielding effectiveness for conformal-shielded SiP and measurement with magnetic probe. , 2015, , .		11
81	Compact hybrid open stub EBG structure for power noise suppression in WLAN band. , 2015, , .		4
82	A SMD-type filter solution for EMI/RFI mitigation on high-speed digital interfaces and its application. , 2015, , .		0
83	Compact wideband balanced filter for eliminating radio-frequency interference on differentially-fed antennas. , 2015, , .		4
84	Tri-section quarter wavelength resonator common mode filter. , 2015, , .		5
85	A prediction method of heat generation in the silicon substrate for 3-D ICs. , 2015, , .		0
86	Estimation Method for Statistical Eye Diagram in a Nonlinear Digital Channel. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 1655-1664.	1.4	19
87	A via-based methodology for frequency selective surface minimization. , 2015, , .		1
88	An Ultra-Compact Common-Mode Bandstop Filter With Modified-T Circuits in Integrated Passive Device (IPD) Process. IEEE Transactions on Microwave Theory and Techniques, 2015, 63, 3624-3631.	2.9	46
89	Suppression of end-fired emission for a miniaturized-element frequency-selective shielding surface with finite size using EBG. , 2015, , .		0
90	A Circular-Ring Miniaturized-Element Metasurface With Many Good Features for Frequency Selective Shielding Applications. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 365-374.	1.4	58

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91	An Effective Via-Based Frequency Adjustment and Minimization Methodology for Single-Layered Frequency-Selective Surfaces. IEEE Transactions on Antennas and Propagation, 2015, 63, 1641-1649.	3.1	48
92	Modeling and Analysis of Bandwidth-Enhanced Multilayer 1-D EBG With Bandgap Aggregation for Power Noise Suppression. IEEE Transactions on Electromagnetic Compatibility, 2015, 57, 858-867.	1.4	7
93	Investigation of signal integrity issues in multi-path electrostatic discharge protection device. , 2015, , .		7
94	A compact dual-band common-mode filtering component for EMC in wireless communication. , 2015, , .		3
95	Design of on-chip microwave filters in integrated fan-out wafer level packaging (InFO-WLP) technology. , 2015, , .		1
96	Very Closely Located Dual-Band Frequency Selective Surfaces via Identical Resonant Elements. IEEE Antennas and Wireless Propagation Letters, 2015, 14, 414-417.	2.4	26
97	A Novel Compact Balun Using a Weakly Coupled Line With Grounded Resonator. IEEE Microwave and Wireless Components Letters, 2014, 24, 763-765.	2.0	6
98	A Compact Loop-Slot Mode Combination Antenna for Ultra-Thin Tablet Computer With Metallic Bottom Cover. IEEE Antennas and Wireless Propagation Letters, 2014, 13, 746-749.	2.4	18
99	A novel common-mode filter (CMF) design based on signal interference technique. , 2014, , .		2
100	Fast prediction of radiation from high-speed/high-density connectors. , 2014, , .		2
101	Statistical eye diagram prediction for a 8b10b-coded channel using pulse response. , 2014, , .		7
102	Miniaturized and bandwidth-enhanced multilayer 1-D EBG structure for power noise suppression. , 2014, , .		5
103	A Novel 2.5-Dimensional Ultraminiaturized-Element Frequency Selective Surface. IEEE Transactions on Antennas and Propagation, 2014, 62, 3657-3663.	3.1	73
104	An Equation-Based Circuit Model and Its Generation Tool for 3-D IC Power Delivery Networks With an Emphasis on Coupling Effect. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1062-1070.	1.4	12
105	A Novel Dual-Function Circuit Combining High-Speed Differential Equalizer and Common-Mode Filter With an Additional Zero. IEEE Microwave and Wireless Components Letters, 2014, 24, 617-619.	2.0	13
106	Synthesis Model and Design of a Common-Mode Bandstop Filter (CM-BSF) With an All-Pass Characteristic for High-Speed Differential Signals. IEEE Transactions on Microwave Theory and Techniques, 2014, 62, 1647-1656.	2.9	59
107	ABF-Based TSV Arrays With Improved Signal Integrity on 3-D IC/Interposers: Equivalent Models and Experiments. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1744-1753.	1.4	25
108	Test Generation of Path Delay Faults Induced by Defects in Power TSV. , 2013, , .		2

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109	Bandwidth Enhancement of 4-Port Butler Matrix Using Broadband Forward-Wave Directional Coupler and Phase Difference Compensation. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 4099-4109.	2.9	36
110	The effect of various skew compensation strategies on mode conversion and radiation from high-speed connectors. , 2013, , .		10
111	A novel common-mode filter for multiple differential pairs with low crosstalk and low mode conversion level. , 2013, , .		1
112	Power distribution network modeling for 3-D ICs with TSV arrays. , 2013, , .		0
113	A Magnetic-Field Resonant Probe With Enhanced Sensitivity for RF Interference Applications. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 991-998.	1.4	59
114	Model and Mechanism of Miniaturized and Stopband-Enhanced Interleaved EBG Structure for Power/Ground Noise Suppression. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 159-167.	1.4	24
115	A Broadband Forward-Wave Directional Coupler Using Periodic Y-Shaped Ground Via Structures With Arbitrary Coupling Levels. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 38-47.	2.9	15
116	Overview of Signal Integrity and EMC Design Technologies on PCB: Fundamentals and Latest Progress. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 624-638.	1.4	166
117	Analytical Design of Via Lattice for Ground Planes Noise Suppression and Application on Embedded Planar EBG Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 21-30.	1.4	27
118	Novel Differential-Mode Equalizer With Broadband Common-Mode Filtering for Gb/s Differential-Signal Transmission. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1578-1587.	1.4	16
119	Active magnetic field canceling system. , 2013, , .		2
120	Compact TSV-based wideband bandpass filters on 3-D IC. , 2013, , .		5
121	Radio-frequency interference mitigation strategies for high-speed connectors. , 2013, , .		6
122	A novel compact 3-dB forward-wave directional coupler with periodic capacitive enhancement. , 2012, , .		1
123	A new solution and its estimation method for slot-crossing signals to reduce ISI-increased crosstalk. , 2012, , .		0
124	Low slow-wave effect and crosstalk for low-cost ABF-coated TSVs in 3-D IC interposer. , 2012, , .		10
125	A Branched Reflector Technique to Reduce Crosstalk Between Slot-Crossing Signal Lines. IEEE Microwave and Wireless Components Letters, 2012, 22, 342-344.	2.0	5
126	A novel dual-functional structure integrating differential-mode equalizer with common-mode filter for Gbps signaling. , 2012, , .		1

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127	A Compact and Embedded Balanced Bandpass Filter With Wideband Common-Mode Suppression on Wireless SiP. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1030-1038.	1.4	32
128	A novel miniaturized bandstop filter using defected ground on system in package (SiP). , 2012, , .		0
129	Signal integrity design for GHz high-speed differential wires with slip ring capsule. , 2012, , .		1
130	Design considerations for radio frequency 3DICs. , 2012, , .		0
131	Eye prediction of digital driver with power distribution network noise. , 2012, , .		7
132	A New Model for Through-Silicon Vias on 3-D IC Using Conformal Mapping Method. IEEE Microwave and Wireless Components Letters, 2012, 22, 303-305.	2.0	40
133	A novel TSV model considering nonlinear MOS effect for transient analysis. , 2012, , .		12
134	Novel crosstalk modeling for multiple through-silicon-vias (TSV) on 3-D IC: Experimental validation and application to Faraday cage design. , 2012, , .		19
135	Radiation Suppression for Cable-Attached Packages Utilizing a Compact Embedded Common-Mode Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 1696-1703.	1.4	69
136	3D simulation of substrate noise coupling from Through Silicon Via (TSV) and noise isolation methods. , 2012, , .		8
137	Bandwidth Enhancement Based on Optimized Via Location for Multiple Vias EBG Power/Ground Planes. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2012, 2, 332-341.	1.4	37
138	Mold-based compartment shielding to mitigate the intra-system coupled noise on SiP modules. , 2011, , .		14
139	A novel common mode choke and its application for 5 Gbps USB 3.0. , 2011, , .		9
140	Evaluation of magnetic field from varied permutation power transmission line at high technology nano-Fab. , 2011, , .		3
141	A broadband and miniaturized balun on system-in-package (SiP) technology. , 2011, , .		0
142	Suppression of RF interference using balanced filter in communication system. , 2011, , .		3
143	A novel and cost-effective method to suppress GHz common-mode radiation for slot-crossing differential lines. , 2011, , .		1
144	Active field canceling system in next generation nano-Fab. , 2011, , .		2

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145	Suppression of Common-Mode Radiation and Mode Conversion for Slot-Crossing GHz Differential Signals Using Novel Grounded Resonators. IEEE Transactions on Electromagnetic Compatibility, 2011, 53, 429-436.	1.4	6
146	A Novel Compact Forward-Wave Directional Coupler Design Using Periodical Patterned Ground Structure. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 1249-1257.	2.9	19
147	A Miniaturized and Broadband Balun Using Artificial Coupled Line With Imaginary Even-Mode Impedance. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 2233-2240.	2.9	5
148	A physics-based model of on-chip decoupling capacitor for accurate power integrity analysis. , 2011, , .		3
149	Analysis and design of GHz power noise isolation using 45&#x00B0; rotated photonic crystal fence. , 2011, , .		3
150	Bandwidth-enhanced EBG structure for power noise suppression in 60 GHz RF SiP. , 2011, , .		1
151	Accuracy-improved through-silicon-via model using conformal mapping technique. , 2011, , .		5
152	Mitigation of Noise Coupling in Multilayer High-Speed PCB: State of the Art Modeling Methodology and EBG Technology. IEICE Transactions on Communications, 2010, E93-B, 1678-1689.	0.4	21
153	A Broadband Chip-Level Power-Bus Model Feasible for Power Integrity Chip-Package Codesign in High-Speed Memory Circuits. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 235-239.	1.4	5
154	Overview of Power Integrity Solutions on Package and PCB: Decoupling and EBG Isolation. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 346-356.	1.4	181
155	Signal/Power Integrity Modeling of High-Speed Memory Modules Using Chip-Package-Board Coanalysis. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 381-391.	1.4	28
156	A Broadband and Miniaturized Common-Mode Filter for Gigahertz Differential Signals Based on Negative-Permittivity Metamaterials. IEEE Transactions on Microwave Theory and Techniques, 2010, 58, 195-202.	2.9	143
157	A Novel Miniaturized Forward-Wave Directional Coupler With Periodical Mushroom-Shaped Ground Plane. IEEE Transactions on Microwave Theory and Techniques, 2010, 58, 2277-2283.	2.9	17
158	An ultra compact common-mode filter for RF Interference control in 3G wireless communication systems. , 2010, , .		3
159	A novel time domain method to extract equivalent circuit model of patterned ground structures. , 2010, , .		0
160	Parallel-plate noise suppression using a ground surface perturbation lattice (GSPL) structure. , 2010, , .		5
161	A new bandstop filter using artificial defected ground structures with compact size and low radiation. , 2010, , .		3
162	A Novel Time Domain Method to Extract Equivalent Circuit Model of Patterned Ground Structures. IEEE Microwave and Wireless Components Letters, 2010, 20, 486-488.	2.0	14

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163	Design and Implementation of a Novel Hybrid Photonic Crystal Power/Ground Layer for Broadband Power Noise Suppression. IEEE Transactions on Advanced Packaging, 2010, 33, 206-211.	1.7	17
164	Design and Modelling of Miniaturized Bandgap Structure for Wideband GHz-Noise Suppression Based on LTCC Technology. IEEE Transactions on Advanced Packaging, 2010, 33, 630-638.	1.7	1
165	A Power Bus With Multiple Via Ground Surface Perturbation Lattices for Broadband Noise Isolation: Modeling and Application in RF-SiP. IEEE Transactions on Advanced Packaging, 2010, 33, 582-591.	1.7	15
166	A Novel Ground Resonator Technique to Reduce Common-Mode Radiation on Slot-Crossing Differential Signals. IEEE Microwave and Wireless Components Letters, 2010, 20, 660-662.	2.0	12
167	A novel and low-cost method for slot-crossing differential line to reduce GHz common-mode radiation in advanced PCB. , 2010, , .		0
168	A new common-mode EMI suppression technique for GHz differential signals crossing slotted reference planes. , 2010, , .		2
169	A stopband enhanced EBG power/ground plane based on via location design. , 2010, , .		2
170	Conformal shielding investigation for SiP modules. , 2010, , .		12
171	Design and Modeling of a Stopband-Enhanced EBG Structure Using Ground Surface Perturbation Lattice for Power/Ground Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 2047-2054.	2.9	44
172	A metamaterial-typed differential transmission line with broadband common-mode suppression. , 2009, , .		9
173	Impact of Photonic Crystal Power/Ground Layer density on power integrity performance of high-speed power buses. , 2009, , .		4
174	An ultra compact electromagnetic band gap filter for GHz power noise suppression using LTCC technology. , 2009, , .		0
175	A GHz common-mode filter using negative permittivity metamaterial on low temperature co-fire ceramic (LTCC) substrate. , 2009, , .		9
176	Signal/power integrity design strategy for low-cost package of high-speed memory I/O interfaces. , 2009, , .		8
177	A Novel Wideband Common-Mode Suppression Filter for Gigahertz Differential Signals Using Coupled Patterned Ground Structure. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 848-855.	2.9	261
178	Anxiety levels in women undergoing prenatal maternal serum screening for Down syndrome: the effect of a fast reporting system by mobile phone short-message service. Prenatal Diagnosis, 2008, 28, 417-421.	1.1	34
179	A Novel Power/Ground Layer Using Artificial Substrate EBG for Simultaneously Switching Noise Suppression. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 1164-1171.	2.9	54
180	Power integrity chip-package-PCB co-simulation for I/O interface of DDR3 high-speed memory. , 2008, , .		9

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181	The effects on SI and EMI for differential coupled microstrip lines over LPC-EBG power/ground planes. , 2008, , .		4
182	Fundamentals of signal integrity. , 2008, , .		1
183	A novel stopband-enhanced EBG planes using an Embedded Slow-wave Structure in Low-cost RF-SiP. , 2008, , .		3
184	An Embedded Common-Mode Suppression Filter for GHz Differential Signals Using Periodic Defected Ground Plane. IEEE Microwave and Wireless Components Letters, 2008, 18, 248-250.	2.0	258
185	A novel HU-shaped common-mode filter for GHz differential signals. , 2008, , .		2
186	A novel broadband common-mode filter for high-speed differential signals. , 2008, , .		3
187	Parallel-plate noise isolation using a macro-via photonic crystal structure in advanced package. , 2008, , .		0
188	Chip-package-board co-design - a DDR3 system design example from circuit designers&#x2019; perspective. , 2008, , .		7
189	A low cost dual-CPW differential line for two layer PCBs. , 2008, , .		0
190	Modeling Noise Coupling Between Package and PCB Power/Ground Planes With an Efficient 2-D FDTD/Lumped Element Method. IEEE Transactions on Advanced Packaging, 2007, 30, 864-871.	1.7	29
191	A Novel EBG Power Plane with Stopband Enhancement using Artificial Substrate. , 2007, , .		7
192	Broadband Noise Suppression Using a Hybrid Photonic Crystal Power/Ground Plane Substrate. , 2007, , .		0
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